

ZEUS Cleaning System

Semi-Automatic Single Wafer Cleaner



Technical Specifications

The Zeus system is capable of cleaning wafers ranging in size from 20mm x 20mm coupon wafers to wafers with diameters up to 300mm, all within a single piece of equipment. This allows for the cleaning of various wafer sizes without the need to change equipment, and the wafers are dried using spin dry after cleaning. Therefore, the cleaning capability can be directly evaluated by measuring the wafers with particle inspection equipment immediately after cleaning. Particularly, since it can clean coupon wafers, it is possible to immediately assess the cleaning performance using AFM after applying new cleaning solutions or new cleaning processes. This flexibility enables the evaluation of cleaning performance without being confined to environments that require Full Scale Particle Counters, which is a requirement for traditional equipment.

Brush Cleaning

Down Force Control	Max 10kgf
Wafer RPM	Max 3000rpm
Brush RPM Control	Max 400rpm
Torque Monitoring	Motor Torque Monitoring
Types of Cleaning Solutions	Max 3 Solutions

Pen Brush or Pad Buffing

Sweep Frequency	Max 30cpm
Wafer RPM Control	Max 3000rpm
Down Force	Max 5kgf
RPM Control	Max 200rpm

Megasonic Cleaning

Sweep Frequency	Max 30cpm
Megasonic Frequency	~1 MHz
Wafer RPM Control	Max 3000rpm

Chemical Rinse Cleaning



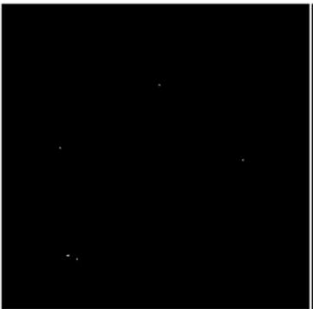


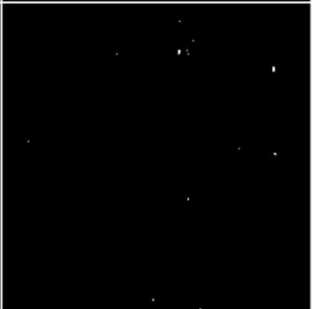
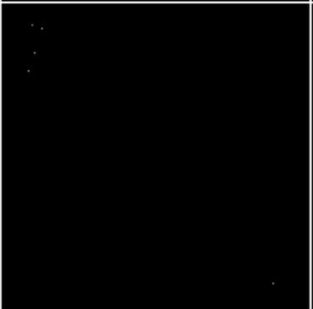
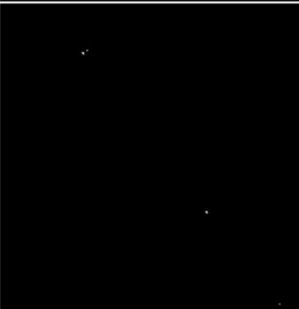

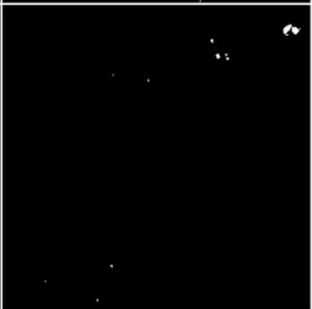
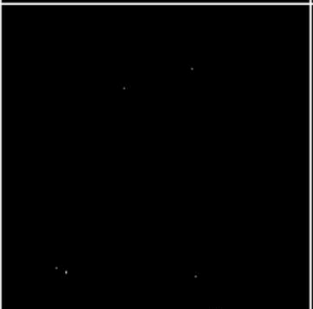
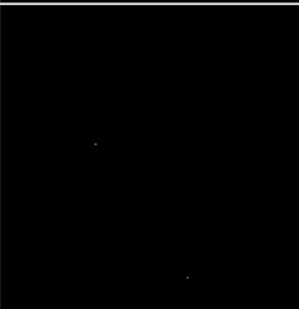
Sweep Frequency	Max 30cpm
Flow Rate Control	Max 1 liter/min
Wafer RPM Control	Max 3000rpm
No. of Chemicals	2 Chemicals

Spin Dry

Blowing	N2 Blowing
Wafer RPM Control	Max 3000rpm, 5sec acc.

Process Results

The Zeus cleaning system is capable of performing chemical spray, megasonic cleaning, pad buffing, and PVA brush cleaning sequentially, and allows for the programming of each process parameter according to recipes. This ensures that the best results can be achieved when applying the appropriate cleaning solutions and process conditions to have a very high particle removal capability.

AFM 3 nm	3 s	5 s	7 s	10 s
SQ50C2 - 0.107 psi				
				
				

AFM measurement results of particles larger than 3nm in diameter after cleaning of a wafer surface with ZEUS cleaner, Source: G&P Technology

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